

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6620072

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	KARTHIK VENKATRAM	02/03/2021
	ANSAH AHMED SHEIK	02/14/2021
	DANIEL AMERGA	12/03/2020
	SHANSHAN WANG	12/01/2020
	ARVIND VARDARAJAN SANTHANAM	11/20/2020
	OZCAN OZTURK	11/21/2020
	MASATO KITAZOE	01/04/2021
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	QUALCOMM INCORPORATED	
<b>Street Address:</b>	5775 MOREHOUSE DRIVE	
<b>City:</b>	SAN DIEGO	
<b>State/Country:</b>	CALIFORNIA	
<b>Postal Code:</b>	92121-1714	
<b>PROPERTY NUMBERS Total: 1</b>		
<b>Property Type</b>	<b>Number</b>	
<b>Application Number:</b>	16929410	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(703)391-2901	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	7033912900	
<b>Email:</b>	ptonoticesqc@marburylaw.com	
<b>Correspondent Name:</b>	THE MARBURY LAW GROUP, PLLC	
<b>Address Line 1:</b>	11800 SUNRISE VALLEY DRIVE	
<b>Address Line 2:</b>	15TH FLOOR	
<b>Address Line 4:</b>	RESTON, VIRGINIA 20191	
<b>ATTORNEY DOCKET NUMBER:</b>	193759 / 1376-2310	
<b>NAME OF SUBMITTER:</b>	LINDA KENAH	
<b>SIGNATURE:</b>	/Linda Kenah/	
<b>DATE SIGNED:</b>	03/24/2021	

PATENT

**Total Attachments: 21**

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**ASSIGNMENT**

WHEREAS, WE,

1. **Karthik VENKATRAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
2. **Ansah Ahmed SHEIK**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
3. **Daniel AMERGA**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
4. **Shanshan WANG**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
5. **Arvind Vardarajan SANTHANAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
6. **Ozcan OZTURK**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**; and
7. **Masato KITAZOE**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MANAGING WIRELESS DEVICE COMMUNICATION WITH A BASE STATION** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not

limited to U.S. Application No(s). **16/929,410** filed **July 15, 2020**, Qualcomm Reference Number **193759**, and all provisional applications relating thereto, together with India Application No. **201941030908**, filed **July 31, 2019**, Qualcomm Reference No. **193759IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at SAN DIEGO, CA, on 02/03/2021  
City, State Date

Karthik VENKATRAM  
Karthik VENKATRAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

\_\_\_\_\_  
Ansah Ahmed SHEIK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

\_\_\_\_\_  
Daniel AMERGA

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

\_\_\_\_\_  
Shanshan WANG

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

\_\_\_\_\_  
Arvind Vardarajan SANTHANAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

\_\_\_\_\_  
Ozcan OZTURK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

\_\_\_\_\_  
Masato KITAZOE

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6. **Ozcan OZTURK**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**; and
7. **Masato KITAZOE**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MANAGING WIRELESS DEVICE COMMUNICATION WITH A BASE STATION** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not

limited to U.S. Application No(s). **16/929,410** filed **July 15, 2020**, Qualcomm Reference Number **193759**, and all provisional applications relating thereto, together with India Application No. **201941030908**, filed **July 31, 2019**, Qualcomm Reference No. **193759IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Karthik VENKATRAM

Done at HYDERABAD, INDIA, on 14/02/2021  
City, State Date

Ansah Ahmed  
Ansah Ahmed SHEIK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Daniel AMERGA

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Shanshan WANG

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Arvind Vardarajan SANTHANAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Ozcan OZTURK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Masato KITAZOE



**ASSIGNMENT**

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limited to U.S. Application No(s). **16/929,410** filed **July 15, 2020**, Qualcomm Reference Number **193759**, and all provisional applications relating thereto, together with India Application No. **201941030908**, filed **July 31, 2019**, Qualcomm Reference No. **193759IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Karthik VENKATRAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Ansah Ahmed SHEIK

Done at San Diego, CA, on 12/03/2020  
City, State Date

  
Daniel AMERGA

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Shanshan WANG

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Arvind Vardarajan SANTHANAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Ozcan OZTURK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date

Masato KITAZOE

**ASSIGNMENT**

WHEREAS, WE,

1. **Karthik VENKATRAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
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limited to U.S. Application No(s). **16/929,410** filed **July 15, 2020**, Qualcomm Reference Number **193759**, and all provisional applications relating thereto, together with India Application No. **201941030908**, filed **July 31, 2019**, Qualcomm Reference No. **193759IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Karthik VENKATRAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Ansah Ahmed SHEIK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Daniel AMERGA

Done at San Diego, CA, on 2/1/2020  
City, State Date   
Shanshan WANG

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Arvind Vardarajan SANTHANAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Ozcan OZTURK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Masato KITAZOE

**ASSIGNMENT**

WHEREAS, WE,

1. **Karthik VENKATRAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
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WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not

limited to U.S. Application No(s). **16/929,410** filed **July 15, 2020**, Qualcomm Reference Number **193759**, and all provisional applications relating thereto, together with India Application No. **201941030908**, filed **July 31, 2019**, Qualcomm Reference No. **193759IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;



AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Karthik VENKATRAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Ansah Ahmed SHEIK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Daniel AMERGA

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Shanshan WANG

Done at SAN DIEGO  
USA, on 11/20/2020  
City, State Date Arvind Vardarajan SANTHANAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Ozcan OZTURK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Masato KITAZOE

**ASSIGNMENT**

WHEREAS, WE,

1. **Karthik VENKATRAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
2. **Ansah Ahmed SHEIK**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
3. **Daniel AMERGA**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
4. **Shanshan WANG**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
5. **Arvind Vardarajan SANTHANAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
6. **Ozcan OZTURK**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**; and
7. **Masato KITAZOE**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MANAGING WIRELESS DEVICE COMMUNICATION WITH A BASE STATION** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not

limited to U.S. Application No(s). **16/929,410** filed **July 15, 2020**, Qualcomm Reference Number **193759**, and all provisional applications relating thereto, together with India Application No. **201941030908**, filed **July 31, 2019**, Qualcomm Reference No. **193759IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.


Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Karthik VENKATRAM

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Ansah Ahmed SHEIK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Daniel AMERGA

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Shanshan WANG

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Arvind Vardarajan SANTHANAM

Done at San Diego, CA, on 11/21/2020  
City, State Date  Ozcan OZTURK

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date Masato KITAZOE

**ASSIGNMENT**

WHEREAS, WE,

1. **Karthik VENKATRAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
2. **Ansah Ahmed SHEIK**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
3. **Daniel AMERGA**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
4. **Shanshan WANG**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
5. **Arvind Vardarajan SANTHANAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;
6. **Ozcan OZTURK**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**; and
7. **Masato KITAZOE**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MANAGING WIRELESS DEVICE COMMUNICATION WITH A BASE STATION** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not

limited to U.S. Application No(s). **16/929,410** filed **July 15, 2020**, Qualcomm Reference Number **193759**, and all provisional applications relating thereto, together with India Application No. **201941030908**, filed **July 31, 2019**, Qualcomm Reference No. **193759IN1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date **Karthik VENKATRAM**


Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date **Ansah Ahmed SHEIK**

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date **Daniel AMERGA**

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date **Shanshan WANG**

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date **Arvind Vardarajan SANTHANAM**

Done at \_\_\_\_\_, on \_\_\_\_\_  
City, State Date **Ozcan OZTURK**

Done at Tokyo, on January 4, 2021  
City, State Date   
**Masato KITAZOE**